



UL recognition, file #E230084
 Glass passivated chip junction
 Ideal for printed circuit boards
 High surge current capability
 Solder dip 275 °C max. 7 s, per JESD 22-B106

General purpose use in AC/DC bridge full wave rectification for monitor, TV, printer, power supply, switching mode power supply, adapter, audio equipment, and home appliances applications.

: GBU

Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant

: Tin plated leads, solderable per

J-STD-002 and JESD22-B102

As marked on body

($T_a=25$ Unless otherwise specified Å

Device marking code				EGBU1506
Maximum Repetitive Peak Reverse Voltage		V_{RRM}	V	600
Maximum RMS Voltage		V_{RMS}	V	420
Maximum DC blocking Voltage		V_{DC}	V	600
Average rectified output current @60Hz sine wave, R-load	With heatsink $T_c=100$ -	I_o	A	15.0
	Without heatsink $T_a=25$ -			2.5
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave, 1 cycle, $T_j=25$		I_{FSM}	A	180
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, $T_j=25$				360



$\dot{A}T_a=25$ - Unless otherwise specified \dot{A}

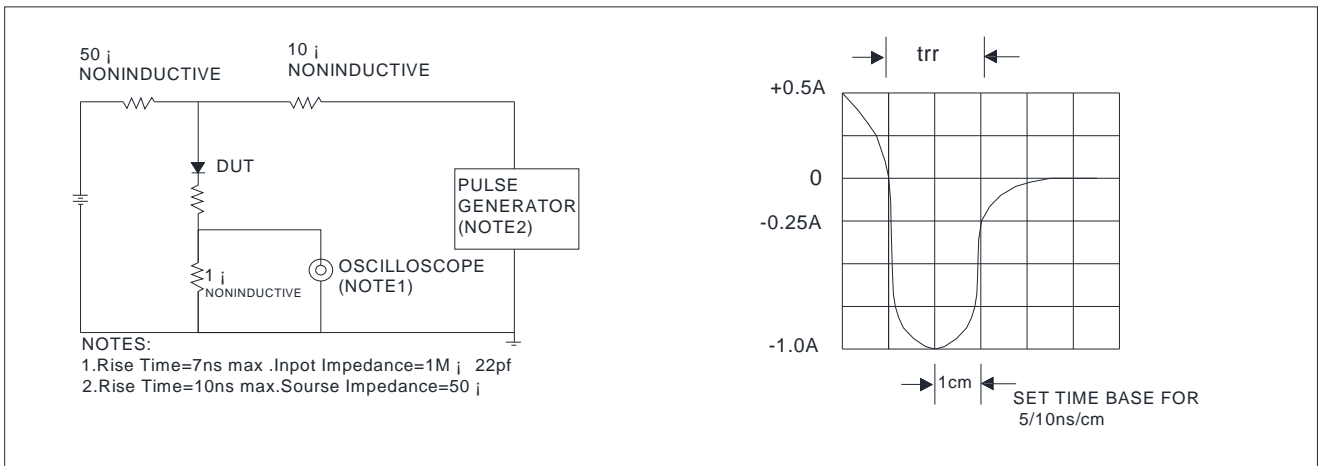
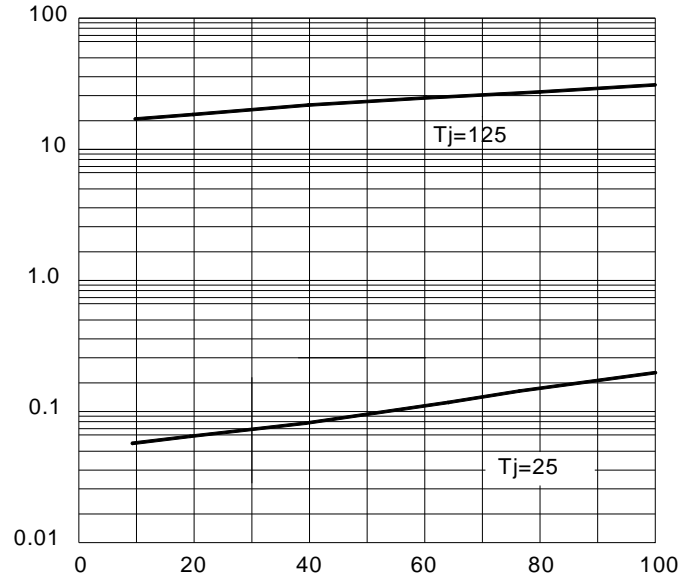
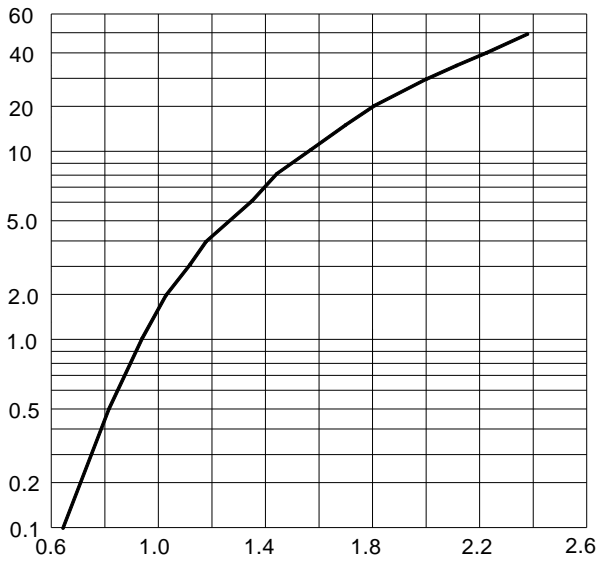
Maximum reverse recovery time	T_{RR}	ns	$I_F=0.5A, I_R=1.0A,$ $I_{RR}=0.25A$	35
Maximum instantaneous forward voltage drop per diode	V_F	V	$I_{FM}=7.5A$	2.0
Maximum DC reverse current at rated DC blocking voltage per diode	I_R	μA	$T_j=25$ -	5
			$T_j=125$ -	100
Typical junction capacitance	C_j	pF	Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	65

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Thermal Resistance	Between junction and ambient, Without heatsink	R_{J-A}	- /W	20
	Between junction and case, With heatsink	R_{J-C}		2

Note: Device mounted on 75mm x 45mm x 5.5mm Aluminum Plate Heatsink.

(Example)





Dim	Min	Max
A	21.80	22.30
B	18.30	18.80
C	17.50	18.00
D	3.30	3.90
E	7.10	7.50
F	5.50	5.90
G	1.91	2.54
H	2.06	2.54
I	1.02	1.27

